

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT5054574

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
MINKYUNG KANG	06/26/2013
YOUNGDAL ROH	06/26/2013
DONG JU JEON	06/26/2013
KYOUNGHEE PARK	06/26/2013
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	STATS CHIPAC LTD.
<b>Street Address:</b>	10 ANG MO KIO STREET 65
<b>Internal Address:</b>	#05-17/20 TECHPOINT
<b>City:</b>	SINGAPORE
<b>State/Country:</b>	SINGAPORE
<b>Postal Code:</b>	569059
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	15433866
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(650)670-8813
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	6506708800
<b>Email:</b>	kcho@wongrees.com, docketing@wongrees.com, krees@wongrees.com
<b>Correspondent Name:</b>	WONG & REES LLP
<b>Address Line 1:</b>	4340 STEVENS CREEK BLVD.
<b>Address Line 2:</b>	SUITE 106
<b>Address Line 4:</b>	SAN JOSE, CALIFORNIA 95129
<b>ATTORNEY DOCKET NUMBER:</b>	70027-2284
<b>NAME OF SUBMITTER:</b>	KARL T. REES
<b>SIGNATURE:</b>	/KarlTRees#58983/
<b>DATE SIGNED:</b>	07/17/2018
This document serves as an Oath/Declaration (37 CFR 1.63).	

**Total Attachments: 7**

source=70027-2284\_Assignment1#page1.tif

source=70027-2284\_Assignment1#page2.tif

source=70027-2284\_Assignment1#page3.tif

source=70027-2284\_Assignment1#page4.tif

source=70027-2284\_Assignment1#page5.tif

source=70027-2284\_Assignment1#page6.tif

source=70027-2284\_Assignment1#page7.tif

**ASSIGNMENT STATEMENT**

Oath/Declaration Statement Included

WHEREAS, the undersigned (hereinafter termed Assignor(s)) has/have invented certain new and useful improvements in

**INTEGRATED CIRCUIT PACKAGING SYSTEM WITH EMBEDDED PAD ON LAYERED SUBSTRATE AND METHOD OF MANUFACTURE THEREOF**

for which a United States patent application has been executed on or before the date of this assignment.

WHEREAS, STATS ChipPAC Ltd., a Corporation of the Republic of Singapore, having a place of business at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, Republic of Singapore (hereinafter termed Assignee), is desirous of acquiring the entire right, title and interest in and to said application and said invention and improvements thereon, and in and to Letters Patents thereon when granted in the United States and foreign countries.

NOW, THEREFORE, for good and valuable consideration received by said Assignor(s) from said Assignee(s), the receipt of which is hereby acknowledged by said Assignor(s):

1. Said Assignor(s) hereby state that I/we have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.
2. Said Assignor(s) does not know/do not know and does not believe/do not believe the same was ever known or used in the United States of America before this invention thereof or more than one year prior to this application, and that the same was not in public use or on sale in the United States of America more than one year prior to this application. I acknowledge the duty to disclose information which is known to me to be material to patentability in accordance with title 37, Code of Federal Regulations, section 1.56.
3. Said Assignor(s) does hereby sell, assign, transfer and convey unto said Assignee(s), the entire right, title and interest in and to said application and said invention and in and to any and all improvements on said invention and in and to any and all improvements on said invention heretofore or hereafter made or acquired by said Assignor(s); and in and to any and all Letters Patent on said invention and/or said improvements that may be granted in the United States or any foreign country, including each and every Letters Patent granted on any application which is a division, continuation, substitution, renewal, or continuation-in-part of any said application, and in and to each and every reissue or extension of said Letters Patent.
4. Said Assignor(s) hereby covenants and agrees to cooperate with said Assignee(s) where said Assignee(s) may enjoy to the fullest extent the right, title and interest herein conveyed. Such cooperation shall include (a) prompt execution of all papers (prepared at the expense of Assignee(s)) which are deemed necessary or desirable by Assignee(s) to perfect in it the right, title and interest herein conveyed, (b) prompt execution of all petitions, oaths, specifications or other papers (prepared at the expense of Assignee(s)) which are deemed necessary or desirable by Assignee(s) for prosecuting said application, for filing and prosecuting divisional, continuation, substitution, renewal, continuation-in-part, or additional applications in the United States and/or foreign countries covering said invention and/or said improvements, for filing and prosecuting applications for reissuance of letters patent included herein, or for interference proceedings involving said invention and/or said improvements and (c) prompt assistance and cooperation in the prosecution of interference proceedings involving said invention and/or said improvements and in the adjudication of said Letters Patent, particularly by the disclosure of facts and the production of evidence relating to said invention and/or said improvements, provided the expenses which may be incurred by said Assignor(s) in lending such assistance and cooperation shall be paid by the Assignee(s).
5. The terms, covenants and conditions of this assignment shall inure to the benefit of said Assignee(s), its successors, assigns and/or other legal representatives and shall be binding upon said Assignor(s), his/her heirs, legal representatives and assigns.

6. Said Assignor(s) hereby warrants and represents that he/she has not entered into any assignment, contract or understanding in conflict herewith.

**Authorization to Permit Access To Application by Participating Office**

If checked, the undersigned hereby grants the USPTO authority to provide the European Patent Office (EPO), the Japan Patent Office (JPO), the Korean Intellectual Property Office (KIPO), the World Intellectual Property Office (WIPO), and any other intellectual property offices in which a foreign application claiming priority to the above-identified patent application is filed access to the above-identified patent application. See 37 CFR 1.14(c) and (h). This box should not be checked if the applicant does not wish the EPO, JPO, KIPO, WIPO, or other intellectual property office in which a foreign application claiming priority to the above-identified patent application is filed to have access to the above-identified patent application.

In accordance with 37 CFR 1.14(h)(3), access will be provided to a copy of the above-identified patent application with respect to: 1) the above-identified patent application –as-filed; 2) any foreign application to which the above-identified patent application claims priority under 35 U.S.C. 119(a)-(d) if a copy of the foreign application that satisfies the certified copy requirement of 37 CFR 1.55 has been filed in the above-identified patent application; and 3) any U.S. application-as-filed form which benefit is sought in the above-identified patent application.

In accordance with 37 CFR 1.14(c), access may be provided to information concerning the date of filing the Authorization to Permit Access to Application by Participating Offices.

7. Said Assignor(s) hereby claim foreign priority benefits under Title 35, United States Code, Section 119(a)-(d) or Section 365(b) of any foreign application(s) for patent or inventor’s certificate, or Section 365(a) of any PCT international application which designated at least one country other than the United States listed below and have also identified below any foreign application for patent or inventor’s certificate having a filing date before that of the application on which priority is claimed:

**Prior Foreign Application(s):**

Number	Country	Day/Month/Year filed	Priority Claimed	
			Yes	No

8. Said Assignor(s) hereby claim the benefit under 35 USC 119(e) of any United States provisional application(s) listed below:

**Prior Provisional Application(s):**

Serial No.	Filing Date

9. Said Assignor(s) hereby claim the benefit under Title 35, United States Code, Section 120 of any United States application(s), or Section 365(c) of any PCT international application designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT international application in the manner provided by the first paragraph of Title 35, United States Code, Section 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, Section 1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

**Prior U.S. Application(s):**

<u>Serial No.</u>	<u>Filing Date</u>




10. Said Assignor(s) hereby authorizes and requests the attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow:

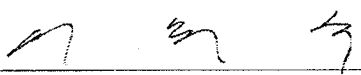
<u>Serial No.</u>	<u>Filing Date</u>
13/928, 754	June 27, 2013

The above-identified application was made or authorized to be made by the Assignor(s), who believe(s) that I am/we are the original inventor(s) or an original joint inventor(s) of a claimed invention in the application.

Said Assignor(s) hereby acknowledge that any willful false statement made in this Assignment is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both. Said Assignor has executed and delivered this instrument on the date set forth below.

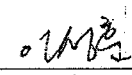
Inventor's signature:  Date: 2013-06-26

Full name of inventor: MinKyung Kang  
Citizenship: Republic of Korea  
Residence Address: 116-908 Hanshin APT Dobong2-Dong  
Dobong-Gu  
Seoul  
Korea  
Post Office Address: c/o STATS ChipPAC Ltd.  
5 Yishun Street 23  
Singapore 768442  
Singapore

  
Witness Signature

Heesoo, Lee  
Print Witness Name

2013-06-26  
Date

  
Witness Signature

Sungbum, Lee  
Print Witness Name


2013-06-26  
Date

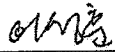
The above-identified application was made or authorized to be made by the Assignor(s), who believe(s) that I am/we are the original inventor(s) or an original joint inventor(s) of a claimed invention in the application.

Said Assignor(s) hereby acknowledge that any willful false statement made in this Assignment is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both. Said Assignor has executed and delivered this instrument on the date set forth below.

Inventor's signature:  Date: 2013-06-26

Full name of inventor: YoungDal Roh  
Citizenship: Republic of Korea  
Residence Address: 3-217 Cheongwon, San 136-1  
Ami-ri, Bubal-eub  
Icheon-si, Gyeonggi-do  
Korea  
Post Office Address: c/o STATS ChipPAC Ltd.  
5 Yishun Street 23  
Singapore 768442  
Singapore

  
Witness Signature

  
Witness Signature

Heehoo, Lee  
Print Witness Name

Sung-hun, Lee  
Print Witness Name

2013-06-26  
Date

2013-06-26  
Date

The above-identified application was made or authorized to be made by the Assignor(s), who believe(s) that I am/we are the original inventor(s) or an original joint inventor(s) of a claimed invention in the application.

Said Assignor(s) hereby acknowledge that any willful false statement made in this Assignment is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both. Said Assignor has executed and delivered this instrument on the date set forth below.

Inventor's signature: Jean Dongju Date: 2013-06-26

Full name of inventor: Dong Ju Jeon  
Citizenship: Republic of Korea  
Residence Address: 101-1303, Woobang Apts.  
Jayangdong, Kwangjin-gu  
Seoul,  
Korea  
Post Office Address: c/o STATS ChipPAC Ltd.  
5 Yishun Street 23  
Singapore 768442  
Singapore

Witness Signature

Witness Signature

Hee Soo, Lee

Print Witness Name

2013-06-26

Date

Witness Signature

Witness Signature

Gung-hum, Lee

Print Witness Name

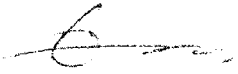
2013-06-26

Date

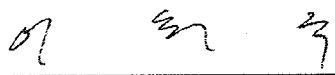


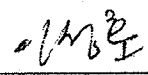
The above-identified application was made or authorized to be made by the Assignor(s), who believe(s) that I am/we are the original inventor(s) or an original joint inventor(s) of a claimed invention in the application.

Said Assignor(s) hereby acknowledge that any willful false statement made in this Assignment is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both. Said Assignor has executed and delivered this instrument on the date set forth below.

Inventor's signature:  Date: 2013-06-26

Full name of inventor: Kyounghee Park  
Citizenship: Republic of Korea  
Residence Address: 106-902, Gandong Hyundai Hometown  
Amsa3 dong, Gangdong-Gu,  
Seoul,  
Korea  
Post Office Address: c/o STATS ChipPAC Ltd.  
5 Yishun Street 23  
Singapore 768442  
Singapore

  
Witness Signature  
Heehoo, Lee  
Print Witness Name  
2013-06-26  
Date

  
Witness Signature  
Gung-hm, Lee  
Print Witness Name  
2013-06-26  
Date